

#### **Device Features**

- Single Fixed 3.3V supply
- Gain = 13.4 dB @ 850MHz
- Output IP3 = 32.3 dBm @ 850MHz
- 5G NR ACLR = 5.3 dBm @ 850MHz
- · Internally matched to 50 ohms
- RoHS2-compliant SOT-363 SMT package

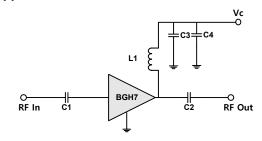
#### **Product Description**

The BGH7 is a BroadBand, HBT Amplifier that is ideal for applications demanding high linearity in a wideband of 10-4200 MHz. The BGH7 is internally matched to 50 Ohms and requires no external matching components. It is available in RoHS2-compliant SOT363 SMT package. These devices are 100% DC and RF tested to assure quality and performance.

#### **Applications**

- Mobile Infrastructure
- LTE / WCDMA / EDGE / 5G NR / WIFI
- General Purpose Wireless

#### **Applications Circuit**



Application Circuit Values Example					
Freq.	0.01 ~ 0.6 ~ 2.4 0.6GHz 2.4GHz 4.2G				
C1	1 nF	100 pF	12 pF		
C2	1 nF	100 pF	2 pF		
C3	100 pF	100 pF	100 pF		
C4	1 nF	1 nF	1 nF		
L1	1.2 uH	100 nH	15 nH		

#### Part Marking (XX:Wafer number)



Pin Description				
RF IN 3				
RF OUT	6			
GND 1,2,4,5				

#### **Electrical Specifications**

Device performance  $\_$  measured on a BeRex evaluation board at 25°C, Vc=3.3V, 50  $\Omega$  system.

Parameter	Conditions	Min	Тур	Max	Unit
Operational Frequency Range		10		4200	MHz
Test Frequency			850		MHz
Gain		11.9	13.4		dB
Input Return Loss			-10.5		dB
Output Return Loss			-16.0		dB
Output IP3	0 dBm / tone , Δf=1 MHz	29.3	32.3		dBm
Output P1dB		14.0	15.0		dBm
5G NR ACLR <sup>*</sup>		4.3	5.3		dBm
Noise Figure			4.9		dB

<sup>\*</sup>ACLR Channel Power measured at -50dBc.

#### **Recommended Operating Conditions**

Parameter	Min	Тур	Max	Unit
Bandwidth	10		4200	MHz
I <sub>C</sub> @ (Vc = 3.3V)	44	55	66	mA
V <sub>C</sub>	3.0	3.3	3.6	V
dG/dT		-0.0008		dB/°C
R <sub>TH</sub>		72.3		°C/W
Operating Case Temperature	-40		+105	°C

 $\label{lem:electrical} \textbf{Electrical specifications are measured at specified test conditions.}$ 

Specifications are not guaranteed over all recommended operating conditions.

#### **Absolute Maximum Ratings**

Parameter	Rating	Unit
Storage Temperature	-55 to +155	°C
Junction Temperature	125	°C
Supply Voltage	+4	V
Supply Current	170	mA
Input RF Power	24	dBm

Operation of this device above any of these parameters may result in permanent damage.

**BeRex** 

•website: www.berex.com

•email: sales@berex.com

<sup>- 5</sup>G set-up: 3GPP 5G NR, 100MHz BW, ±100MHz offset, PAR 9.5 at 0.01% Prob.

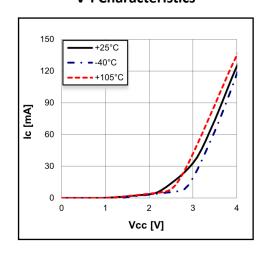


## Typical Performance (Vc=3.3V, Ic=55mA, T=25°C)

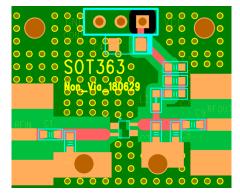
Parameter				Frequency				Unit
	70	500	850	1950	2140	2600	3500	MHz
Gain	13.6	13.4	13.4	13.0	12.8	13.0	13.3	dB
S11	-11.0	-11.3	-10.7	-13.4	-15.0	-15.4	-16.3	dB
S22	-15.0	-15.8	-16.2	-32.7	-30.1	-13.3	-12.9	dB
OIP3	33.0	33.0	33.3	28.3	27.6	28.0	23.7	dBm
P1dB	14.7	14.8	15.0	14.7	14.4	14.4	13.0	dBm
LTE 20M ACLR*	5.5	5.5	5.3	4.6	4.3	4.5	-	dBm
5G NR ACLR <sup>*</sup>	-	-	-	-	-	-	0.5	dBm
Noise Figure	4.57	4.77	4.85	5.70	5.87	5.81	6.71	dB

<sup>\*</sup>ACLR Channel Power measured at -50dBc.

#### **V-I Characteristics**



## **BeRex SOT-363 Evaluation Board**



\*Dielectric constant \_ 4.2 \*RF pattern width 52mil \*31mil thick FR4

<sup>-</sup> LTE set-up: 3GPP LTE, FDD E-TM3.1, 20MHz BW, ±20MHz offset, PAR 9.75 at 0.01% Prob.

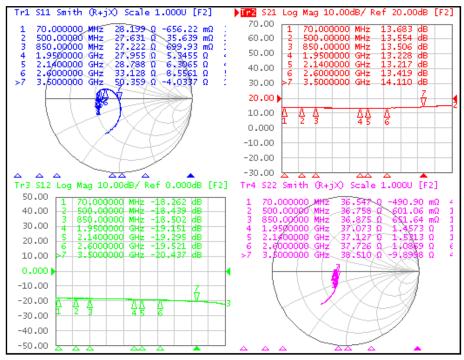
<sup>- 5</sup>G set-up: 3GPP 5G NR, 100MHz BW, ±100MHz offset, PAR 9.5 at 0.01% Prob.

<sup>\*</sup>Without vias under device degrade device performance.



## **Typical Device Data**

S-parameters (V<sub>c</sub>=3.3V, I<sub>c</sub>=55mA, T=25°C, Bias Tee Data)



## **S-Parameter**

 $(V_c = 3.3V, I_c = 55mA, T = 25 ^{\circ}C, calibrated to device leads, Bias Tee Data)$ 

Freq	S11	S11	S21	S21	S12	S12	S22	S22
[MHz]	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
100	0.28	-178.33	4.82	-175.44	0.12	-0.93	0.16	-178.65
500	0.29	179.74	4.75	160.21	0.12	-6.21	0.15	177.57
1000	0.30	176.50	4.72	141.52	0.12	-12.53	0.15	176.31
1500	0.30	169.67	4.64	122.36	0.11	-19.24	0.15	174.26
2000	0.29	161.45	4.58	10.4.32	0.11	-25.96	0.15	172.66
2500	0.24	150.35	4.65	85.89	0.11	-32.64	0.14	172.78
3000	0.14	134.58	4.79	65.86	0.10	-43.19	0.12	-174.44
3500	0.04	-81.94	5.09	43.29	0.09	-56.55	0.17	-132.56
4000	0.35	-95.22	5.59	14.18	0.09	-81.16	0.41	-120.74
4200	0.51	-110.87	5.51	-2.00	0.07	-95.40	0.56	-127.10

BeRex

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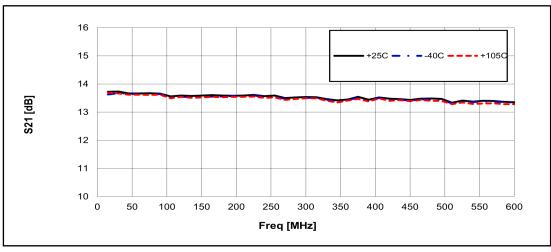


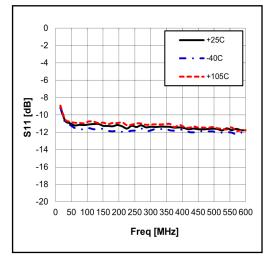
# RF Application Circuit: 10 – 600MHz

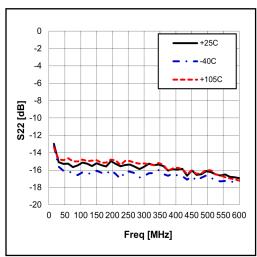
Schematic Diagram		вом	Size(inch)
Vc □ □ □ □	C1	1 nF	0603
BGH7 C2 RF Out	C2	1 nF	0603
	C3	100 pF	0603
	C4	1 nF	0603
	L1	1.2 uH	0603

# **Typical Performance**

 $V_c = 3.3V$ ,  $I_c = 55mA$ ,  $T=25^{\circ}C$ 





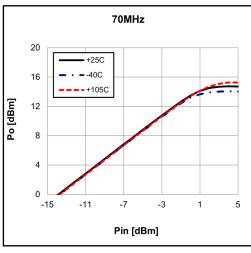


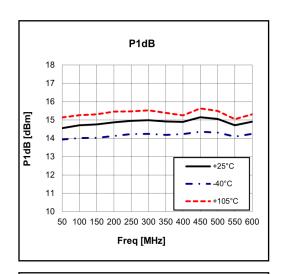
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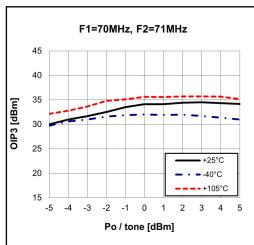
•website: www.berex.com

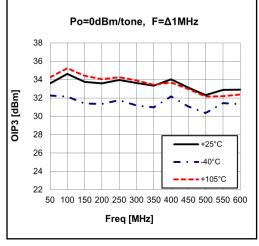
●email: sales@berex.com

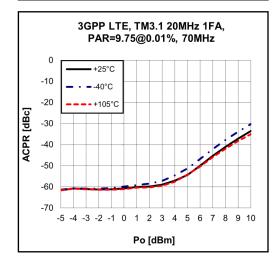


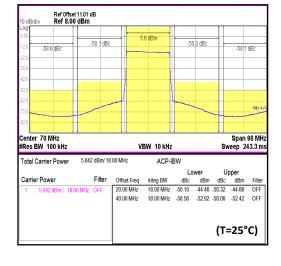




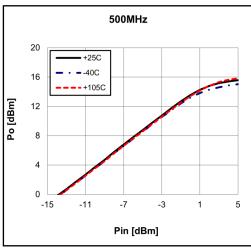


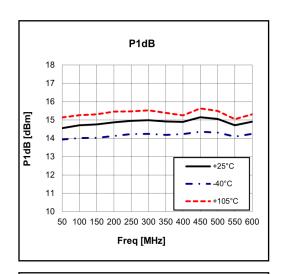


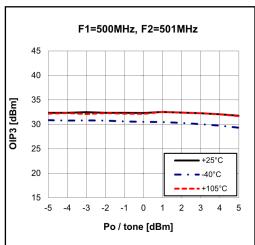


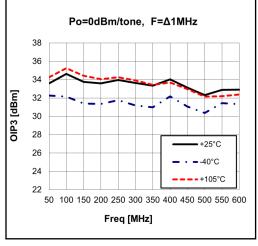


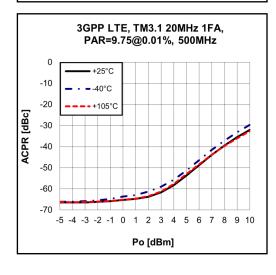


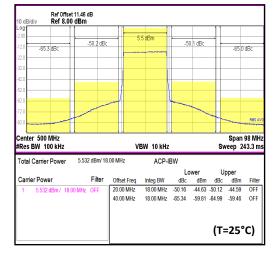












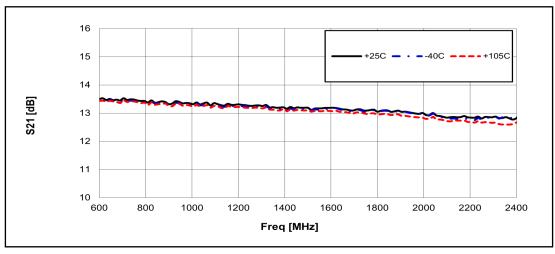


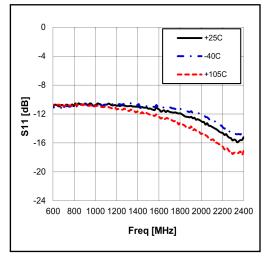
# RF Application Circuit: 600 - 2400MHz

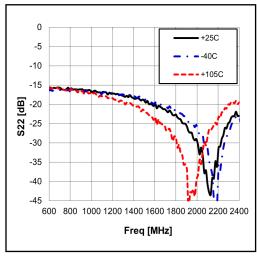
Schematic Diagram		вом	Size(inch)
Vc □ □ □ □	C1	100 pF	0603
C3 C4  L1 BGH7  RF In C1 C2 RF Out	C2	100 pF	0603
	С3	100 pF	0603
	C4	1 nF	0603
	L1	100 nH	0603

# **Typical Performance**

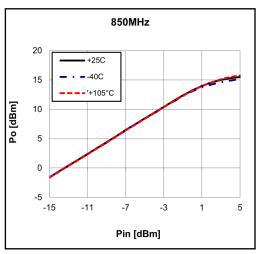
 $V_c = 3.3V$ ,  $I_c = 55mA$ ,  $T=25^{\circ}C$ 

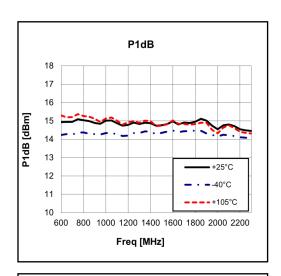


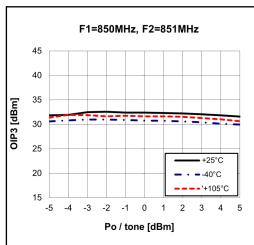


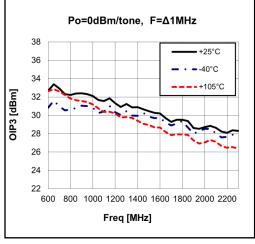


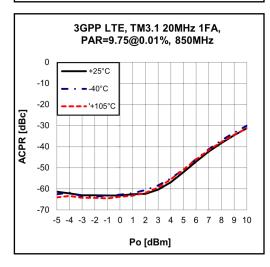


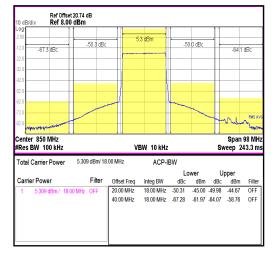




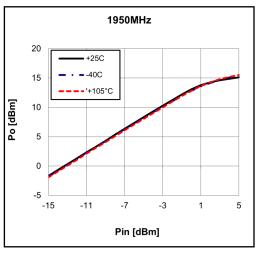


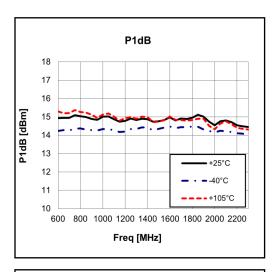


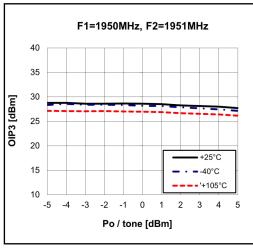


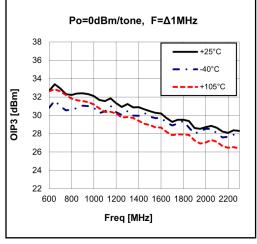


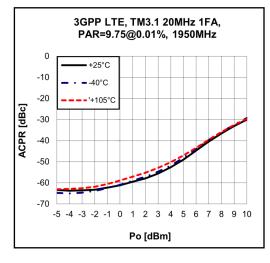


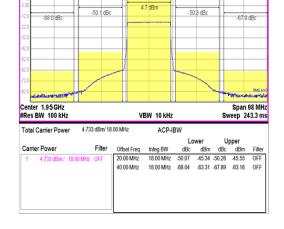






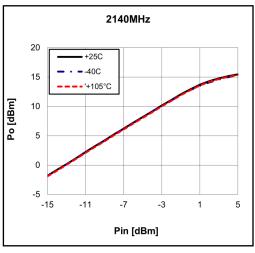


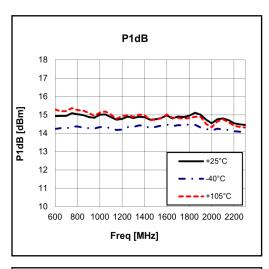


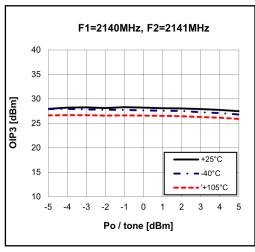


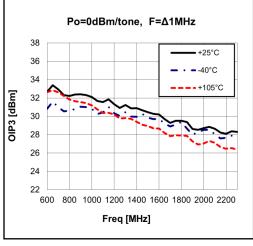
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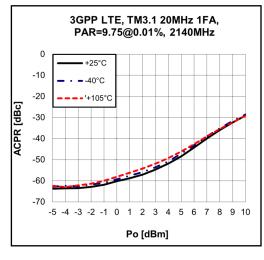


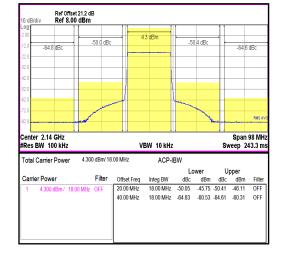












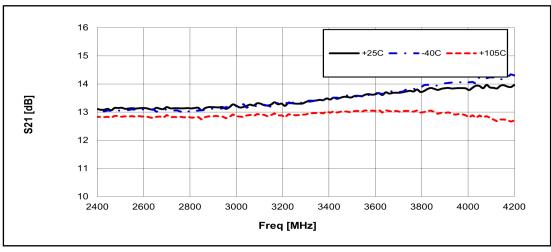


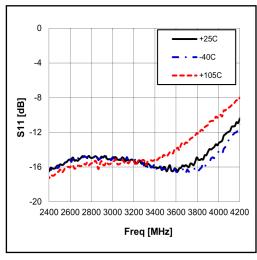
# RF Application Circuit: 2400 - 4200MHz

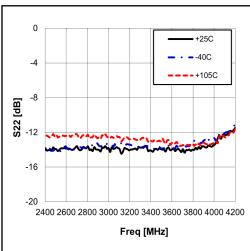
Schematic Diagram		вом	Size(inch)
Vc ○	C1	12 pF	0603
BGH7 C2 RF Out	C2	2 pF	0603
	C3	100 pF	0603
	C4	1 nF	0603
	L1	15 nH	0603

# **Typical Performance**

 $V_c = 3.3V$ ,  $I_c = 55mA$ ,  $T=25^{\circ}C$ 





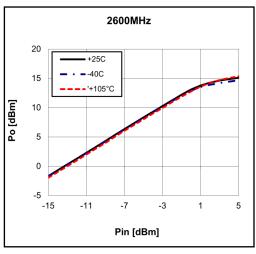


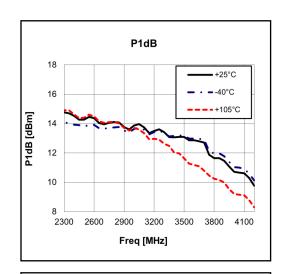
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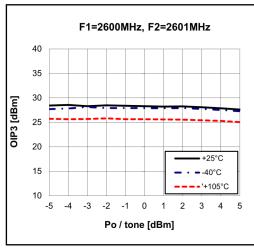
•website: www.berex.com

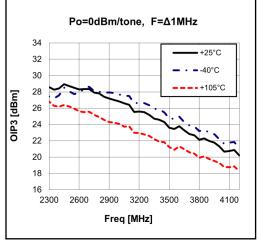
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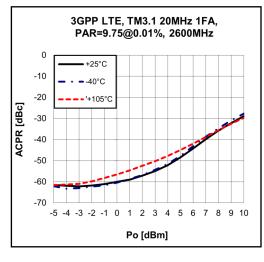


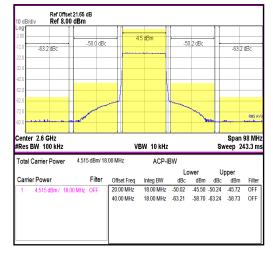




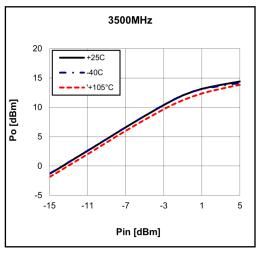


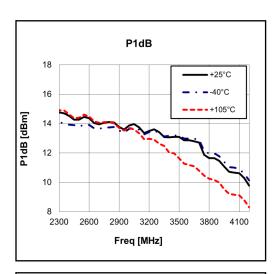


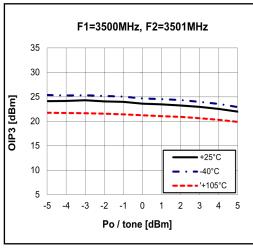


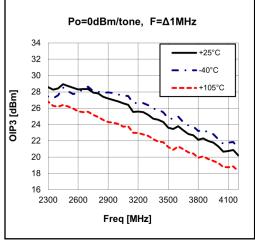


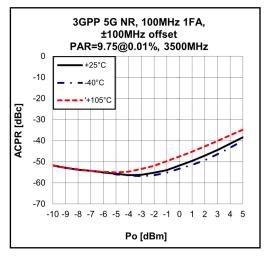


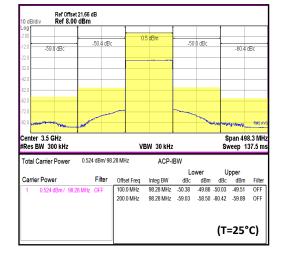






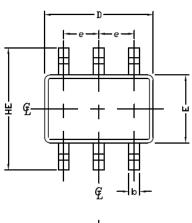


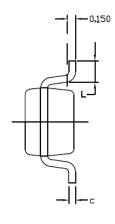




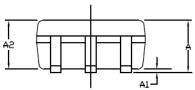


# **Package Outline Dimension**





SYMBOL	MIN	MAX	
E	1.15	1,35	
D	1,85	2,25	
HE	2,00	2,30	
A	0.80	1,00	
A2	0.80	0.91	
A1	0.00	0.09	
е	0.65 BSC		
b	0.15	0.30	
U	0.08	0.25	
٦	0.21	0.41	

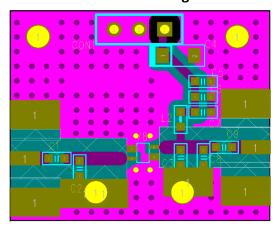


# **Suggested PCB Land Pattern and PAD Layout**

## **PCB Land Pattern**

#### 0.380 0.450 0.450 0.450 0.450 0.450 0.450 0.745 0.570 0.

#### **PCB Mounting**

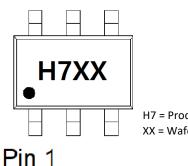


Note: All dimension \_ millimeters

PCB lay out  $\_$  on BeRex website

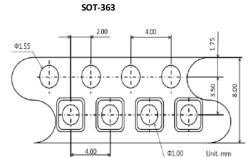


# **Package Marking**



H7 = Product No. XX = Wafer No.

# Tape & Reel



Packaging information:

Tape Width (mm): 8

Reel Size (inches): 7

Device Cavity Pitch (mm): 4

Devices Per Reel: 3000

# Lead plating finish

#### 100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)

## MSL / ESD Rating

**ESD Rating:** Class 1B

Passes <1000V Value:

Test: Human Body Model (HBM) JEDEC Standard JS-001-2017 Standard:

MSL Rating: Level 1 at +260°C convection reflow

Standard: JEDEC Standard J-STD-020



Proper ESD procedures should be followed when handling this device.

**BeRex** 

•website: www.berex.com

•email: sales@berex.com



#### **RoHS Compliance**

This part is compliant with Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) Directive 2011/65/EU as amended by Directive 2015/863/EU. This product also is compliant with a concentration of the Substances of Very High Concern (SVHC) candidate list which are contained in a quantity of less than 0.1%(w/w) in each components of a product and/or its packaging placed on the European Community market by the BeRex and Suppliers.

## **NATO CAGE code:**

2 N 9 6 F	:
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